Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A ~~composition containing~~ composition, comprising: an organic conductive material and at least one species of solvent, wherein the changing rate of the viscosity is within a range of ±5% when 30 days have passed after the preparation.

2. (Currently Amended) The composition according to Claim 1, ~~wherein~~ the solvent ~~contains~~ containing a glycol medium.

3. (Currently Amended) The composition according to Claim 2, ~~wherein~~ the content of the glycol medium in the solvent ~~ranges~~ ranging from 40 to 55 percent by weight.

4. (Currently Amended) The composition according to Claim 2, ~~wherein~~ the glycol medium ~~includes~~ including diethylene glycol and a mixture containing the same.

5. (Currently Amended) The composition according to Claim 2, ~~wherein~~ the glycol medium ~~includes~~ including monoethylene glycol and a mixture containing the same.

6. (Currently Amended) The composition according to Claim 2, ~~wherein~~ the glycol medium ~~includes~~ including triethylene glycol and a mixture containing the same.

7. (Currently Amended) The composition according to Claim 1, ~~wherein~~ the organic conductive material ~~includes~~ including polythiophene derivatives.

8. (Currently Amended) The composition according to Claim 1, ~~wherein~~ the organic conductive material ~~includes~~ including a mixture of polydioxythiophene and polystyrene sulfonic acid.

9. (Currently Amended) The composition according to Claim 1, ~~wherein~~ the organic conductive material ~~includes~~ including a mixture of polyaniline and polystyrene sulfonic acid.

10. (Currently Amended) The composition according to Claim 2, ~~wherein~~ the solvent ~~contains~~ containing an acetylenic ~~glycol~~ alcohol surfactant.

11. (Currently Amended) The composition according to Claim 10, ~~wherein~~ the content of the acetylenic ~~glycol~~ alcohol surfactant in the solvent ~~ranges~~ ranging from 0.01 to 0.1 percent by weight.

12. (Currently Amended) The composition according to Claim 10, ~~wherein~~ the acetylenic ~~glycol~~ alcohol surfactant ~~has~~ having a boiling point that is less than or equal to that of the medium as well as the surfactant contained in the solvent.

13. (Currently Amended) The composition according to Claim 10, ~~wherein~~ the acetylenic ~~glycol~~ alcohol surfactant includes 3,5-dimethyl-1-octyne-3-ol.

14. (Currently Amended) The composition according to Claim 1, ~~wherein~~ the composition ~~is~~ being subjected to degassing treatment.

15. (Currently Amended) The composition according to Claim 14, ~~wherein~~ the degassing treatment ~~is~~ being performed at a vacuum pressure that is less than or equal to the saturation vapor pressure of water.

16. (Currently Amended) The composition according to Claim 14, ~~wherein~~ before the degassing treatment, the composition ~~contains~~ containing an amount of the medium vaporized in the degassing treatment in advance.

17. (Currently Amended) An organic semiconductive ~~layer comprising~~ layer, comprising:

a composition according to ~~any one of Claims 1 to 16.~~ Claim 1.

18. (Currently Amended) A method ~~for manufacturing~~ to manufacture organic conductive layers, ~~comprising~~ comprising:

~~an application step of~~ applying a composition to different portions by an inkjet process, the composition being set forth in ~~any one of Claims 1 to 16.~~ Claim 1.

19. (Currently Amended) The organic conductive layer-manufacturing method according to ~~Claim 18~~ Claim 18, further ~~comprising a drying step of~~ comprising:

removing a solvent after the application step.

20. (Currently Amended) The organic conductive layer-manufacturing method according to Claim 19, ~~wherein~~ the ~~drying step is~~ removing being performed in a vacuum atmosphere.

21. (Currently Amended) The organic conductive layer-manufacturing method according to Claim 20, ~~wherein~~ the ~~drying step is~~ removing being performed at a pressure of 1.333×10^{-3} Pa or less and a temperature substantially equal to room temperature.

22. (Currently Amended) The organic conductive layer-manufacturing method according to ~~Claim 19~~ Claim 19, further ~~comprising a heating step of~~ comprising:

performing thermal treatment at 100°C or more after the ~~drying step.~~removing.

23. (Currently Amended) The organic conductive layer-manufacturing method according to Claim 22, ~~wherein~~ a heat source used in the ~~heating step includes~~ thermal treatment including infrared rays.

24. (Currently Amended) An organic EL ~~element comprising~~ element, comprising:

a hole injection/transport layer ~~comprising~~ including the organic conductive layer according to Claim 17.

25. (Currently Amended) A method ~~for manufacturing~~ to manufacture organic EL elements, ~~comprising a step of~~ comprising: forming hole injection/transport layers each ~~comprising~~ including the organic conductive layer according to Claim 17 by an inkjet process.

26. (Currently Amended) An electronic ~~device comprising~~ device, comprising:

_____at least the organic EL element according to Claim 24 and a circuit ~~for driving~~ to drive the organic EL element.

27. (Currently Amended) An electronic ~~apparatus comprising~~ apparatus, comprising:

_____the electronic device according to Claim 26.

28. (Currently Amended) An organic semiconductor ~~element comprising~~ element, comprising:

_____a source, a drain, a gate or wiring lines, which are conductive portions included in an integrated circuit, each ~~comprising~~ including the organic conductive layer according to Claim 17.

29. (Currently Amended) A method for manufacturing organic semiconductor elements, ~~comprising a step of~~ comprising:

_____forming a drain, a gate or wiring lines, which are conductive portions included in an integrated circuit, by an inkjet process using the organic conductive layer according to Claim 17.